



## Material Content Data Sheet



<b>Sales Product Name</b>		BCR 198 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000451114						
<b>Package</b>		PG-SOT23-3-11		<b>Weight*</b>		8.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.06		569	
	non noble metal	arsenic	7440-38-2	0.000	0.00		3	
	inorganic material	silicon	7440-21-3	0.043	0.49	0.55	4858	5430
leadframe	non noble metal	chromium	7440-47-3	0.008	0.09		924	
	inorganic material	silicon	7440-21-3	0.001	0.01		62	
	non noble metal	titanium	7440-32-6	0.003	0.03		308	
	non noble metal	copper	7440-50-8	2.704	30.68	30.81	306810	308104
wire	noble metal	gold	7440-57-5	0.025	0.28	0.28	2816	2816
encapsulation	organic material	carbon black	1333-86-4	0.058	0.66		6555	
	plastics	brominated resin	-	0.087	0.98		9833	
	inorganic material	antimonytrioxide	1309-64-4	0.116	1.31		13111	
	plastics	epoxy resin	-	1.242	14.09		140943	
	inorganic material	silicondioxide	60676-86-0	4.276	48.51	65.55	485104	655546
leadfinish	non noble metal	tin	7440-31-5	0.150	1.70	1.70	16977	16977
plating	noble metal	silver	7440-22-4	0.098	1.11	1.11	11127	11127
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com